MOOV

Technical Specifications

Parameter	Specification	Notes
Power Supply	230V AC, 50/60Hz	Single Phase
Power Consumption	3kW (Maximum)	1.5kW during normal operation
Inspection Method	Optical Inspection	Laser-based
Wafer Size	150mm, 200mm	Automatic recognition
Resolution	0.1µm	Minimum defect detection
Throughput	60 seconds/wafer	Standard inspection mode
Operating System	Windows-based	Dedicated software
Interface	SECS/GEM	Factory automation support

Main System

- Candela CS10 Main Unit
- Optical Inspection Module
- Wafer Handling System
- Laser Light Source Unit

Control System Industrial

- Monitor (19-inch) Dedicated
- Keyboard Trackball Mouse
- Emergency Stop Button
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